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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

2 0 0 0 0 0	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	8MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	32KB (16K x 16)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	902 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24.23x24.23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17lc756at-08i-l

Email: info@E-XFL.COM

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Pin Diagrams cont.'d



Register	Address	Power-on Reset Brown-out Reset	MCLR Reset WDT Reset	Wake-up from SLEEP through Interrupt
Bank 4		·		·
PIR2	10h	000- 0010	000- 0010	uuu- uuuu (1)
PIE2	11h	000- 0000	000- 0000	uuu- uuuu
Unimplemented	12h			
RCSTA2	13h	x00-0000	0000 -00u	uuuu -uuu
RCREG2	14h	XXXX XXXX	uuuu uuuu	uuuu uuuu
TXSTA2	15h	00001x	00001u	uuuuuu
TXREG2	16h	XXXX XXXX	uuuu uuuu	uuuu uuuu
SPBRG2	17h	0000 0000	0000 0000	นนนน นนนน
Bank 5				
DDRF	10h	1111 1111	1111 1111	uuuu uuuu
PORTF ⁽⁴⁾	11h	0000 0000	0000 0000	uuuu uuuu
DDRG	12h	1111 1111	1111 1111	uuuu uuuu
PORTG ⁽⁴⁾	13h	xxxx 0000	uuuu 0000	uuuu uuuu
ADCON0	14h	0000 -0-0	0000 -0-0	uuuu uuuu
ADCON1	15h	000- 0000	000- 0000	uuuu uuuu
ADRESL	16h	XXXX XXXX	uuuu uuuu	uuuu uuuu
ADRESH	17h	xxxx xxxx	uuuu uuuu	นนนน นนนน
Bank 6				
SSPADD	10h	0000 0000	0000 0000	uuuu uuuu
SSPCON1	11h	0000 0000	0000 0000	uuuu uuuu
SSPCON2	12h	0000 0000	0000 0000	uuuu uuuu
SSPSTAT	13h	0000 0000	0000 0000	uuuu uuuu
SSPBUF	14h	XXXX XXXX	uuuu uuuu	นนนน นนนน
Unimplemented	15h			
Unimplemented	16h			
Unimplemented	17h			

TABLE 5-4:	INITIALIZATION CONDITIONS FOR SPECIAL FUNCTION REGISTERS ((CONTINUED)	

Legend: u = unchanged, x = unknown, - = unimplemented, read as '0', q = value depends on condition

Note 1: One or more bits in INTSTA, PIR1, PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GLINTD bit is cleared, the PC is loaded with the interrupt vector.

3: See Table 5-3 for RESET value of specific condition.

4: This is the value that will be in the port output latch.

5: When the device is configured for Microprocessor or Extended Microcontroller mode, the operation of this port does not rely on these registers.

6: On any device RESET, these pins are configured as inputs.

7.2.2.1 ALU Status Register (ALUSTA)

The ALUSTA register contains the status bits of the Arithmetic and Logic Unit and the mode control bits for the indirect addressing register.

As with all the other registers, the ALUSTA register can be the destination for any instruction. If the ALUSTA register is the destination for an instruction that affects the Z, DC, C, or OV bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Therefore, the result of an instruction with the ALUSTA register as destination may be different than intended.

For example, the CLRF ALUSTA, F instruction will clear the upper four bits and set the Z bit. This leaves the ALUSTA register as 0000u1uu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions be used to alter the ALUSTA register, because these instructions do not affect any status bits. To see how other instructions affect the status bits, see the "Instruction Set Summary."

Note 1: The C and DC bits operate as a borrow and
digit borrow bit, respectively, in subtraction.
See the SUBLW and SUBWF instructions for
examples.

2: The overflow bit will be set if the 2's complement result exceeds +127, or is less than -128.

The Arithmetic and Logic Unit (ALU) is capable of carrying out arithmetic or logical operations on two operands, or a single operand. All single operand instructions operate either on the WREG register, or the given file register. For two operand instructions, one of the operands is the WREG register and the other is either a file register, or an 8-bit immediate constant.

REGISTER 7-1: ALUSTA REGISTER (ADDRESS: 04h, UNBANKED)

	R/W-1	R/W-1	R/W-1	R/W-1	R/W-x	R/W-x	R/W-x	R/W-x
	FS3	FS2	FS1	FS0	OV	Z	DC	С
	bit 7							bit 0
bit 7-6	00 = Post a 01 = Post a	FSR1 Mode auto-decreme auto-increme value does	ent FSR1 va ent FSR1 val					
bit 5-4	00 = Post a 01 = Post a	FSR0 Mode auto-decreme auto-increme value does	ent FSR0 va ent FSR0 val					
bit 3	magnitude 1 = Overflo		es the sign b or signed ar	it (bit7) to ch	ange state.	licates an over	flow of the	7-bit
bit 2		sult of an arit sult of an arit						
bit 1	For ADDWF 1 = A carry	arry/borrow b and ADDLW -out from the ry-out from the	instructions. e 4th Iow ord			ed		
	Note:	For borrow,	the polarity i	s reversed.				
bit 0	C: Carry/bo	orrow bit						
	complement For rotate of source reg 1 = A carry	nt of the seco (RRCF, RLCF)	ond operand) instructions e Most Signif	s, this bit is lo icant bit of th	aded with e	s executed by ither the high c urred	U U	
	Note:	For borrow,	the polarity i	s reversed.				
	Legend:							
	R = Reada	ble bit	W = W	ritable bit	U = Unim	plemented bit	, read as '0	,

'1' = Bit is set

- n = Value at POR Reset

x = Bit is unknown

'0' = Bit is cleared

13.2 Timer3

Timer3 is a 16-bit timer consisting of the TMR3H and TMR3L registers. TMR3H is the high byte of the timer and TMR3L is the low byte. This timer has an associated 16-bit period register (PR3H/CA1H:PR3L/CA1L). This period register can be software configured to be a another 16-bit capture register.

When the TMR3CS bit (TCON1<2>) is clear, the timer increments every instruction cycle (Fosc/4). When TMR3CS is set, the counter increments on every falling edge of the RB5/TCLK3 pin. In either mode, the TMR3ON bit must be set for the timer/counter to increment. When TMR3ON is clear, the timer will not increment or set flag bit TMR3IF.

Timer3 has two modes of operation, depending on the CA1/PR3 bit (TCON2<3>). These modes are:

- Three capture and one period register mode
- · Four capture register mode

The PIC17C7XX has up to four 16-bit capture registers that capture the 16-bit value of TMR3 when events are detected on capture pins. There are four capture pins

(RB0/CAP1, RB1/CAP2, RG4/CAP3, and RE3/CAP4), one for each capture register pair. The capture pins are multiplexed with the I/O pins. An event can be:

- · A rising edge
- A falling edge
- · Every 4th rising edge
- · Every 16th rising edge

Each 16-bit capture register has an interrupt flag associated with it. The flag is set when a capture is made. The capture modules are truly part of the Timer3 block. Figure 13-5 and Figure 13-6 show the block diagrams for the two modes of operation.

13.2.1 THREE CAPTURE AND ONE PERIOD REGISTER MODE

In this mode, registers PR3H/CA1H and PR3L/CA1L constitute a 16-bit period register. A block diagram is shown in Figure 13-5. The timer increments until it equals the period register and then resets to 0000h on the next timer clock. TMR3 Interrupt Flag bit (TMR3IF) is set at this point. This interrupt can be disabled by clearing the TMR3 Interrupt Enable bit (TMR3IE). TMR3IF must be cleared in software.

FIGURE 13-5: TIMER3 WITH THREE CAPTURE AND ONE PERIOD REGISTER BLOCK DIAGRAM



Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	MCLR, WDT
16h, Bank 1	PIR1	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TX1IF	RC1IF	x000 0010	u000 0010
17h, Bank 1	PIE1	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TX1IE	RC1IE	0000 0000	0000 0000
13h, Bank 0	RCSTA1	SPEN	RX9	SREN	CREN		FERR	OERR	RX9D	x00-000x	0000 -00u
16h, Bank 0	TXREG1	TX7	TX6	TX5	TX4	TX3	TX2	TX1	TX0	xxxx xxxx	uuuu uuuu
15h, Bank 0	TXSTA1	CSRC	TX9	TXEN	SYNC	_	_	TRMT	TX9D	00001x	00001u
17h, Bank 0	SPBRG1	Baud Rate	Generato	r Register						0000 0000	0000 0000
10h, Bank 4	PIR2	SSPIF	BCLIF	ADIF	—	CA4IF	CA3IF	TX2IF	RC2IF	000- 0010	000- 0010
11h, Bank 4	PIE2	SSPIE	BCLIE	ADIE	_	CA4IE	CA3IE	TX2IE	RC2IE	000- 0000	000- 0000
13h, Bank 4	RCSTA2	SPEN	RX9	SREN	CREN	_	FERR	OERR	RX9D	0000 - 00x	0000 -00u
16h, Bank 4	TXREG2	TX7	TX6	TX5	TX4	TX3	TX2	TX1	TX0	xxxx xxxx	uuuu uuuu
15h, Bank 4	TXSTA2	CSRC	TX9	TXEN	SYNC		—	TRMT	TX9D	00001x	00001u
17h, Bank 4	SPBRG2	Baud Rate	Generato	r Register					-	0000 0000	0000 0000

TABLE 14-8: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Legend: x = unknown, u = unchanged, - = unimplemented, read as a '0'. Shaded cells are not used for synchronous master transmission.

FIGURE 14-8: SYNCHRONOUS TRANSMISSION



FIGURE 14-9: SYNCHRONOUS TRANSMISSION (THROUGH TXEN)



15.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP) MODULE

The Master Synchronous Serial Port (MSSP) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D converters, etc. The MSSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit[™] (I²C)

Figure 15-1 shows a block diagram for the SPI mode, while Figure 15-2 and Figure 15-3 show the block diagrams for the two different l^2C modes of operation.



FIGURE 15-2:

I²C SLAVE MODE BLOCK DIAGRAM





I²C MASTER MODE BLOCK DIAGRAM



15.2.1.1 Addressing

Once the MSSP module has been enabled, it waits for a START condition to occur. Following the START condition, the 8-bits are shifted into the SSPSR register. All incoming bits are sampled with the rising edge of the clock (SCL) line. The value of register SSPSR<7:1> is compared to the value of the SSPADD register. The address is compared on the falling edge of the eighth clock (SCL) pulse. If the addresses match and the BF and SSPOV bits are clear, the following events occur:

- a) The SSPSR register value is loaded into the SSPBUF register on the falling edge of the 8th SCL pulse.
- b) The buffer full bit, BF, is set on the falling edge of the 8th SCL pulse.
- c) An ACK pulse is generated.
- d) SSP interrupt flag bit, SSPIF (PIR2<7>), is set (interrupt is generated if enabled) - on the falling edge of the 9th SCL pulse.

In 10-bit address mode, two address bytes need to be received by the slave. The five Most Significant bits (MSbs) of the first address byte specify if this is a 10-bit address. Bit R/\overline{W} (SSPSTAT<2>) must specify a write so the slave device will receive the second address byte. For a 10-bit address, the first byte would equal '1111 0 A9 A8 0', where A9 and A8 are the two MSbs of the address. The sequence of events for a 10-bit address is as follows, with steps 7- 9 for slave-transmitter:

- 1. Receive first (high) byte of Address (bits SSPIF, BF and bit UA (SSPSTAT<1>) are set).
- Update the SSPADD register with second (low) byte of Address (clears bit UA and releases the SCL line).
- 3. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.
- 4. Receive second (low) byte of Address (bits SSPIF, BF and UA are set).

- 5. Update the SSPADD register with the first (high) byte of Address. This will clear bit UA and release the SCL line.
- 6. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.
- 7. Receive Repeated Start condition.
- 8. Receive first (high) byte of Address (bits SSPIF and BF are set).
- 9. Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.

Note: Following the Repeated Start condition (step 7) in 10-bit mode, the user only needs to match the first 7-bit address. The user does not update the SSPADD for the second half of the address.

15.2.1.2 Slave Reception

When the R/\overline{W} bit of the address byte is clear and an address match occurs, the R/\overline{W} bit of the SSPSTAT register is cleared. The received address is loaded into the SSPBUF register.

When the address byte overflow condition exists, then no acknowledge (ACK) pulse is given. An overflow condition is defined as either bit BF (SSPSTAT<0>) is set, or bit SSPOV (SSPCON1<6>) is set.

An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF (PIR2<7>) must be cleared in software. The SSPSTAT register is used to determine the status of the received byte.

Note: The SSPBUF will be loaded if the SSPOV bit is set and the BF flag is cleared. If a read of the SSPBUF was performed, but the user did not clear the state of the SSPOV bit before the next receive occurred, the ACK is not sent and the SSP-BUF is updated.

	ts as Data s Received	SSPSR $ ightarrow$ SSPBUF	Generate ACK Pulse	Set bit SSPIF (SSP Interrupt occurs
BF	SSPOV		Fuise	if enabled)
0	0	Yes	Yes	Yes
1	0	No	No	Yes
1	1	No	No	Yes
0	1	Yes	No	Yes

TABLE 15-2: DATA TRANSFER RECEIVED BYTE ACTIONS

Note 1: Shaded cells show the conditions where the user software did not properly clear the overflow condition.

15.2.18.3 Bus Collision During a STOP Condition

Bus collision occurs during a STOP condition if:

- a) After the SDA pin has been de-asserted and allowed to float high, SDA is sampled low after the BRG has timed out.
- b) After the SCL pin is de-asserted, SCL is sampled low before SDA goes high.

The STOP condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the baud rate generator is loaded with SSPADD<6:0> and counts down to '0'. After the BRG times out, SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0'. If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 15-40).

FIGURE 15-40: BUS COLLISION DURING A STOP CONDITION (CASE 1)



FIGURE 15-41: BUS COLLISION DURING A STOP CONDITION (CASE 2)



15.4 Example Program

Example 15-2 shows MPLAB[®] C17 'C' code for using the I²C module in Master mode to communicate with a 24LC01B serial EEPROM. This example uses the PIC[®] MCU 'C' libraries included with MPLAB C17.

EXAMPLE 15-2: INTERFACING TO A 24LC01B SERIAL EEPROM (USING MPLAB C17)

```
// Include necessary header files
#include <p17c756.h>
                       // Processor header file
                       // Delay routines header file
// Standard Library header file
#include <delays.h>
#include <stdlib.h>
                       // Standard Lizzard
// I2C routines header file
#include <i2c16.h>
#define CONTROL 0xa0
                        // Control byte definition for 24LC01B
// Function declarations
void main(void);
void WritePORTD(static unsigned char data);
void ByteWrite(static unsigned char address, static unsigned char data);
unsigned char ByteRead(static unsigned char address);
void ACKPoll(void);
// Main program
void main(void)
{
static unsigned char address; // I2C address of 24LC01B
static unsigned char datao; // Data written to 24LC01B
static unsigned char datai;
                                // Data read from 24LC01B
                                  // Preset address to 0
    address = 0;
   OpenI2C(MASTER,SLEW_ON);
                                 // Configure I2C Module Master mode, Slew rate control on
   SSPADD = 39;
                                 // Configure clock for 100KHz
    while(address<128)
                                 // Loop 128 times, 24LC01B is 128x8
    {
        datao = PORTB;
        do
        {
            ByteWrite(address,datao); // Write data to EEPROM
            ACKPoll();
                                        // Poll the 24LC01B for state
            datai = ByteRead(address); // Read data from EEPROM into SSPBUF
        while(datai != datao);
                                        // Loop as long as data not correctly
                                         11
                                             written to 24LC01B
        address++;
                                        // Increment address
    }
    while(1)
                                         // Done writing 128 bytes to 24LC01B, Loop forever
    {
        Nop();
    }
```

16.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires a minimum 12TAD per 10-bit conversion. The source of the A/D conversion clock is software selected. The four possible options for TAD are:

- 8Tosc
- 32Tosc
- 64Tosc
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 $\mu s.$

Table 16-1 and Table 16-2 show the resultant TAD times derived from the device operating frequencies and the A/D clock source selected. These times are for standard voltage range devices.

TABLE 16-1: TAD VS. DEVICE OPERATING FREQUENCIES (STANDARD DEVICES (C))

AD Clock S	Source (TAD)	Max Fosc
Operation	ADCS1:ADCS0	(MHz)
8Tosc	00	5
32Tosc	01	20
64Tosc	10	33
RC	11	_

Note: When the device frequency is greater than 1 MHz, the RC A/D conversion clock source is only recommended for SLEEP operation.

TABLE 16-2: TAD VS. DEVICE OPERATING FREQUENCIES (EXTENDED VOLTAGE DEVICES (LC))

AD Clock	Source (TAD)	Max Fosc
Operation	ADCS1:ADCS0	(MHz)
8Tosc	00	2.67
32Tosc	01	10.67
64Tosc	10	21.33
RC	11	—

Note: When the device frequency is greater than 1 MHz, the RC A/D conversion clock source is only recommended for SLEEP operation.



16.7 A/D Accuracy/Error

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, TAD should be derived from the device oscillator.

The absolute accuracy specified for the A/D converter includes the sum of all contributions for quantization error, integral error, differential error, full scale error, offset error, and monotonicity. It is defined as the maximum deviation from an actual transition versus an ideal transition for any code. The absolute error of the A/D converter is specified at < \pm 1 LSb for VDD = VREF (over the device's specified operating range). However, the accuracy of the A/D converter will degrade as VREF diverges from VDD.

For a given range of analog inputs, the output digital code will be the same. This is due to the quantization of the analog input to a digital code. Quantization error is typically \pm 1/2 LSb and is inherent in the analog to digital conversion process. The only way to reduce quantization error is to increase the resolution of the A/D converter or oversample.

Offset error measures the first actual transition of a code versus the first ideal transition of a code. Offset error shifts the entire transfer function. Offset error can be calibrated out of a system or introduced into a system through the interaction of the total leakage current and source impedance at the analog input.

Gain error measures the maximum deviation of the last actual transition and the last ideal transition adjusted for offset error. This error appears as a change in slope of the transfer function. The difference in gain error to full scale error is that full scale does not take offset error into account. Gain error can be calibrated out in software.

Linearity error refers to the uniformity of the code changes. Linearity errors cannot be calibrated out of the system. Integral non-linearity error measures the actual code transition versus the ideal code transition, adjusted by the gain error for each code.

Differential non-linearity measures the maximum actual code width versus the ideal code width. This measure is unadjusted.

The maximum pin leakage current is specified in the Device Data Sheet electrical specification (Table 20-2, parameter #D060).

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, TAD should be derived from the device oscillator. TAD must not violate the minimum and should be minimized to reduce inaccuracies due to noise and sampling capacitor bleed off. In systems where the device will enter SLEEP mode after the start of the A/D conversion, the RC clock source selection is required. In this mode, the digital noise from the modules in SLEEP are stopped. This method gives high accuracy.

16.8 Connection Considerations

If the input voltage exceeds the rail values (VSS or VDD) by greater than 0.3V, then the accuracy of the conversion is out of specification.

An external RC filter is sometimes added for antialiasing of the input signal. The R component should be selected to ensure that the total source impedance is kept under the 10 k Ω recommended specification. Any external components connected (via hi-impedance) to an analog input pin (capacitor, zener diode, etc.) should have very little leakage current at the pin.

16.9 Transfer Function

The transfer function of the A/D converter is as follows: the first transition occurs when the analog input voltage (VAIN) equals Analog VREF / 1024 (Figure 16-7).

FIGURE 16-7: A/D TRANSFER FUNCTION



17.4.2 MINIMIZING CURRENT CONSUMPTION

To minimize current consumption, all I/O pins should be either at VDD, or VSS, with no external circuitry drawing current from the I/O pin. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should be at VDD or VSS. The contributions from on-chip pull-ups on PORTB should also be considered and disabled, when possible.

17.5 Code Protection

The code in the program memory can be protected by selecting the microcontroller in Code Protected mode (PM2:PM0 = '000').

In this mode, instructions that are in the on-chip program memory space, can continue to read or write the program memory. An instruction that is executed outside of the internal program memory range will be inhibited from writing to, or reading from, program memory.

Note: Microchip does not recommend code protecting windowed devices.

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

DEC	CF	Decremer	nt f		0
Syn	tax:	[label]	DECF f,d		S
Ope	erands:	$\begin{array}{l} 0 \leq f \leq 255 \\ d \in [0,1] \end{array}$	5		C
Оре	eration:	$(f)-1 \rightarrow ($	dest)		C
Stat	us Affected:	OV, C, DC	;, Z		
Enc	oding:	0000	011d ff	ff ffff	S
Des	cription:	result is sto	register 'f'. If ' red in WREG. red back in re	If 'd' is 1, the	E
Wor	ds:	1			
Сус	les:	1			
QC	ycle Activity:				
	Q1	Q2	Q3	Q4	
	Decode	Read register 'f'	Process Data	Write to destination	V
<u>Exa</u>	<u>mple</u> : Before Instru CNT		CNT, 1		C
	Z	= 0			
	After Instruct CNT Z	tion = 0x00 = 1			lf

DEC	FSZ	Decreme	nt f, ski	p if 0	
Synt	ax:	[label]	DECFS	Z f,d	
Ope	rands:	$0 \le f \le 255$ $d \in [0,1]$	5		
Ope	ration:	(f) – 1 \rightarrow (skip if res			
Statu	us Affected:	None			
Enco	oding:	0001	011d	ffff	ffff
Desc	cription:	The conten mented. If ' WREG. If 'c back in reg If the result which is alr and a NOP it a two-cyc	d' is 0, th l' is 1, th ister 'f'. is 0, the eady feto s execut	e result is e result is next inst ched is di ted instea	placed in placed ruction, scarded
Wor	ds:	1			
Cycl	es:	1(2)			
QC	cle Activity:				
	Q1	Q2	Q	3	Q4
	Decode	Read register 'f'	Proce Dat		Write to estination
lf ski					
lf ski				a de	
lf ski	ip:	register 'f'	Dat	a de B	estination
	ip: Q1 No	register 'f' Q2 No	Dat Q3 No	a de 3 tion c	Q4 No peration
<u>Exar</u>	p: Q1 No operation	Register 'f' Q2 No operation HERE NZERO ZERO Juction	Dat Q3 No opera	a de	Q4 No peration

MO	VLR	Move Lite BSR	eral to hi	igh nibb	le in	
Synt	ax:	[label]	MOVLR	k		
Ope	rands:	$0 \le k \le 15$				
Ope	ration:	$k \rightarrow (BSR)$	<7:4>)			
Statu	us Affected:	None				
Enc	oding:	1011	101x	kkkk	uuuu	
Des	cription:	The 4-bit literal 'k' is loaded into the most significant 4-bits of the Bank Select Register (BSR). Only the high 4-bits of the Bank Select Register are affected. The lower half of the BSR is unchanged. The assembler will encode the "u" fields as 0.				
Wor	ds:	1				
Cyc	les:	1				
QC	ycle Activity:					
	Q1	Q2	Q3		Q4	
	Decode	Read literal 'k'	Proce: Data	a lite	Write eral 'k' to SR<7:4>	
	<u>mple</u> : Before Instru	MOVLR 5	i	·		
	BSR regi	ster = 0x	22			
	After Instruct BSR regi		52			

MO\	/LW	Move Lit	eral to V	VREG	6			
Synt	ax:	[label]	MOVLW	/ k				
Ope	rands:	$0 \le k \le 2$	55					
Ope	ration:	$k \rightarrow (WR)$	EG)					
Statu	us Affected:	None						
Enco	oding:	1011	0000	kkk	k	kkkk		
Desc	cription:	The eight- WREG.	bit literal '	k' is lo	ade	d into		
Wor	ds:	1						
Cycl	es:	1						
QC	cle Activity:							
	Q1	Q2	Q	3		Q4		
	Decode	Read literal 'k'		Process Data		Vrite to VREG		
<u>Exar</u>	<u>mple</u> :	MOVLW	0x5A					

After Instruction WREG = 0x5A

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RET	FIE	Return fro	om Interrupt	t	RE	TLW	Return Li	teral to WR	EG
Synt	ax:	[label]	RETFIE		Syr	ntax:	[label]	RETLW k	
Ope	rands:	None			Op	erands:	$0 \le k \le 25$	5	
Ope	ration:	TOS \rightarrow (P 0 \rightarrow GLIN PCLATH is		L	·	eration:	PCLÀTH i	EG); TOS \rightarrow s unchanged	
Stati	us Affected:	GLINTD	sunchanged			tus Affected:	None		
	oding:		0000 000	00 0101	End	coding:	1011	0110 kk	kk kkkk
	cription:	Return from and Top-of- PC. Interrup the GLINTE	n Interrupt. Sta	ck is POP'ed loaded in the d by clearing is the global		scription: rds:	'k'. The pro the top of th	gram counter he stack (the re ddress latch (F	eight-bit literal is loaded from eturn address). PCLATH)
Wor	ds:	1				les:	2		
Cycl	es:	2				Cycle Activity:	2		
QC	ycle Activity:					Q1	Q2	Q3	Q4
	Q1	Q2	Q3	Q4		Decode	Read	Process	POP PC
	Decode	No operation	Clear GLINTD	POP PC from stack			literal 'k'	Data	from stack, Write to WREG
	No operation	No operation	No operation	No operation		No	No	No	No
						operation	operation	operation	operation
	mple: After Interrup PC GLINTD	= TOS			Exa	ample:	CALL TAI TABLE ADDWF P RETLW K RETLW K : : RETLW KI	; offset ; WREG n ; table C ; WREG = 0 ; Begin t 1 ;	ow has value offset able

Before Instruction

WREG = 0x07

After Instruction

WREG = value of k7

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SUBWF	Subt	act	WREG	from	n f	
Syntax:			SUBWF			
Operands:	0 ≤ f ≤ d ∈ [0	- ≤ 25		,-		
Operation: $(f) - (W) \rightarrow (dest)$						
Status Affected: OV, C, DC, Z						
Encoding:	000	0	010d	fff	f	ffff
Description:	compl result	btract WREG from register 'f' (2's nplement method). If 'd' is 0, the ult is stored in WREG. If 'd' is 1, the ult is stored back in register 'f'.				
Words:	1					
Cycles:	1					
Q Cycle Activity:						
Q1	Q2		Q3			Q4
Decode	Read register		Proces Data		-	Vrite to stination
L	regiotor	•	Data		40	
Example 1: Before Instru REG1 WREG C	SUBWE uction = 3 = 2 = 2	F .	REG1, 1	L		
After Instruc REG1 WREG C Z	•	;	result is p	ositiv	'e	
Example 2:						
Before Instr REG1 WREG C	uction = 2 = 2 = ?					
After Instruc REG1 WREG C Z	tion = 0 = 2 = 1 = 1	;	result is z	ero		
Example 3:						
Before Instru REG1 WREG C	uction = 1 = 2 = ?					
After Instruc REG1 WREG C Z	tion = FF = 2 = 0 = 0	;	result is n	egati	ve	

SUBWFB		-	Subtract Borrow	t WREG	fron	ח f א	/ith		
Syntax:		[label]	SUBWF	З f,o	b			
Operands	:	-	$\begin{array}{l} 0 \leq f \leq 255 \\ d \in [0,1] \end{array}$						
Operation	:	(1	f) – (W)	$-\overline{C} \rightarrow (c$	dest)				
Status Aff	ected:	C	OV, C, DC, Z						
Encoding		Γ	0000 001d ffff ffff						
Descriptic	in:	(I n s	borrow) f nent metl tored in \	WREG an rom regis hod). If 'd' WREG. If ' ck in regis	ter 'f' is 0, d' is 1	(2's the r I , the	comple- esult is		
Words:		1							
Cycles:		1							
Q Cycle A	ctivity:								
(Q1		Q2	Q3			Q4		
De	code		Read	Proce			Vrite to		
		reę	gister 'f'	Data	3	de	stination		
Example		UBWFB	REG1,	1					
	e Instru REG1	ictioi =	n 0x19	(0001	100	7)			
	VREG	=	0x0D	(00001		'			
()	=	1						
F		ion = = = =	0x0C 0x0D 1 0	(0000 (0000 ; result	110	1)	е		
Example2		SU	BWFB 1	REG1,0					
-	 e Instru								
F	REG1 VREG	= = =	0x1B 0x1A 0	(0001 (0001		,			
F		ion = = =	0x1B 0x00 1 1	(0001 ; result		,			
Example3	5	SU	BWFB 1	REG1,1					
	e Instru			,					
F	REG1 VREG	= = =	0x03 0x0E 1	(0000 (0000					
F		ion = = = =	0xF5 0x0E 0 0	(1111 (0000 ; result	110	1)	's comp] ve		

Param. No.	Sym	Charac	teristic	Min	Тур†	Max	Units	Conditions
A01	NR	Resolution		_	_	10	bit	$\label{eq:VREF+} \begin{array}{l} VDD = 5.12V,\\ VSS \leq VAIN \leq VREF+ \end{array}$
				_	_	10	bit	$(VREF+ - VREF-) \ge 3.0V,$ $VREF- \le VAIN \le VREF+$
A02	Eabs	Absolute error		_	_	< ±1	LSb	$\label{eq:VREF+} \begin{array}{l} VDD = 5.12V,\\ VSS \leq VAIN \leq VREF+ \end{array}$
				—	—	< ±1	LSb	$(VREF+ - VREF-) \ge 3.0V,$ $VREF- \le VAIN \le VREF+$
A03	EIL	Integral linearity	error		-	< ±1	LSb	$\label{eq:VREF+} \begin{array}{l} VDD = 5.12V,\\ VSS \leq VAIN \leq VREF+ \end{array}$
				_	-	< ±1	LSb	$(VREF+ - VREF-) \ge 3.0V,$ $VREF- \le VAIN \le VREF+$
A04	Edl	Differential linear	ity error			< ±1	LSb	$\label{eq:VREF+} \begin{array}{l} VDD = 5.12V,\\ VSS \leq VAIN \leq VREF+ \end{array}$
				_	_	< ±1	LSb	$(VREF+ - VREF-) \ge 3.0V,$ $VREF- \le VAIN \le VREF+$
A05	Efs	Full scale error		_	_	< ±1	LSb	$\label{eq:VREF+} \begin{array}{l} VDD = 5.12V,\\ VSS \leq VAIN \leq VREF+ \end{array}$
				_	_	< ±1	LSb	$(VREF+ - VREF-) \ge 3.0V,$ $VREF- \le VAIN \le VREF+$
A06	EOFF	Offset error		_	_	< ±1	LSb	$\label{eq:VREF+} \begin{array}{l} VREF+ = VDD = 5.12V,\\ VSS \leq VAIN \leq VREF+ \end{array}$
				_	_	< ±1	LSb	$(VREF+ - VREF-) \ge 3.0V,$ $VREF- \le VAIN \le VREF+$
A10	—	Monotonicity		—	guaranteed ⁽³⁾		—	$VSS \leq VAIN \leq VREF$
A20	Vref	Reference voltage (VREF+ — VREF-	,	0V		_	V	VREF delta when changing voltage levels on VREF inputs
A20A				3V	_	_	V	Absolute minimum electrical spec. to ensure 10-bit accuracy
A21	VREF+	Reference voltag	ge high	Avss + 3.0V	—	Avdd + 0.3V	V	
A22	VREF-	Reference voltag	ge low	Avss - 0.3V	_	Avdd - 3.0V	V	
A25	VAIN	Analog input volt	age	Avss - 0.3V		Vref + 0.3V	V	
A30	Zain	Recommended i analog voltage s		—	_	10.0	kΩ	
A40	IAD	A/D conversion	PIC17CXXX	_	180		μΑ	Average current consumption when
		current (VDD)	PIC17LCXXX	_	90	_	μΑ	A/D is on (Note 1)
A50	IREF	VREF input curre	nt (Note 2)	10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN
				_	_	10	μA	During A/D conversion cycle

TABLE 20-18: A/D C(ONVERTER CHARACTERISTICS
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† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RG0 and RG1 pins or AVDD and AVSS pins, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the Input Voltage and has no missing codes.

21.0 PIC17C7XX DC AND AC CHARACTERISTICS

The graphs and tables provided in this section are for design guidance and are not tested nor guaranteed. In some graphs or tables the data presented is outside specified operating range (e.g., outside specified VDD range). This is for information only and devices are ensured to operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time.

- Typ or Typical represents the mean of the distribution at 25°C.
- Max or Maximum represents (mean + 3 σ) over the temperature range of -40°C to 85°C.
- Min or Minimum represents (mean 3σ) over the temperature range of -40°C to 85° C.
- **Note:** Standard deviation is denoted by sigma (σ).

TABLE 21-1: PIN CAPACITANCE PER PACKAGE TYPE

Pin Name	Typical Capacitance (pF)			
	68-pin PLCC	64-pin TQFP		
All pins, except MCLR, VDD, and Vss	10	10		
MCLR pin	20	20		

FIGURE 21-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE



84-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)

For the most current package drawings, please see the Microchip Packaging Specification located Note: at http://www.microchip.com/packaging



		INCHES*		MILLIMETERS				
Dimensi	on Limits	MIN	NOM	MAX	MIN	MIN NOM		
Number of Pins	n		68			68		
Pitch	р		.050			1.27		
Pins per Side	n1		17			17		
Overall Height	Α	.165	.173	.180	4.19	4.39	4.57	
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06	
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89	
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86	
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27	
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25	
Overall Width	E	.985	.990	.995	25.02	25.15	25.27	
Overall Length	D	.985	.990	.995	25.02	25.15	25.27	
Molded Package Width	E1	.950	.954	.958	24.13	24.23	24.33	
Molded Package Length	D1	.950	.954	.958	24.13	24.23	24.33	
Footprint Width	E2	.890	.920	.930	22.61	23.37	23.62	
Footprint Length	D2	.890	.920	.930	22.61	23.37	23.62	
Lead Thickness	С	.008	.011	.013	0.20	0.27	0.33	
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81	
Lower Lead Width	В	.013	.020	.021	0.33	0.51	0.53	
Mold Draft Angle Top	α	0	5	10	0	5	10	
Mold Draft Angle Bottom	β	0	5	10	0	5	10	

* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MO-047 Drawing No. C04-093